



**Circuit
Assembly
Adhesives**

SELECTOR GUIDE

Product	Work Life@ Room Temperature	Cure Schedule(s)	Die Shear Strength (80 mil ² IC)	Volume Resistivity	Weight Loss @ 300°C	Meets 5011	Storage Life
Electrically Conductive							
ABLEBOND® 84-1LMI	2 weeks	1 hr @ 150°C or 2 hrs @ 125°C or 1 yr @ -40°C	6500 psi	0.0002 ohm-cm	0.19%	yes	3 mths @ 5°C or 6 mths @ -10°C
Silver-filled, solvent-free, high purity adhesive for microelectronic chip bonding. Apply by screen printing, automatic dispensing or hand probe.							
ABLEBOND 84-1LMI T 1	2 weeks	1 hr @ 150°C or 2 hrs @ 125°C or 1 yr @ -40°C	6600 psi	0.0001 ohm-cm	0.16 %	yes	3 mths @ 5°C or 6 mths @ -10°C
Thermally conductive, screen printable version of 84-1LMI adhesive.							
ABLEBOND 967-1	2 days	6 hrs @ 65°C or 15 min @ 150°C	3300 psi	0.015 ohm-cm	0.52%	no	Premixed & Frozen: 1 yr @ -40°C Kits: 6 mths @ 25°C
Silver-filled, solvent-free epoxy designed for applications which require electrical conductivity and lower cure temperatures. Available premixed and frozen and in two-part kits.							
ABLEBOND 976-1	8 hrs	1 hr @ 150°C	1800 psi	0.0002 ohm-cm	0.20 %	no	Premixed & Frozen: 1 yr @ -40°C Kits: 1 yr @ 25°C
Silver-filled, extremely flexible epoxy designed for use on non-rigid substrates, both for circuitry formation and component attach. Available premixed and frozen and in two-part kits.							
ABLEBOND 8175	2 weeks	1 hr @ 130°C or 30 min @ 150°C	6200 psi	0.0005 ohm-cm	0.30%	yes	6 mths @ -10°C or 1 yr @ -40°C
Silver-filled, stress-absorbing epoxy adhesive designed for surface mount component attach. When applied by printing it is capable of extremely fine pitch resolution. Also available in faster cure versions.							
ABLEBOND 8175 A	24 hrs	3 min @ 150°C or 6 min @ 130°C	5500 psi	0.0003 ohm-cm	0.40 %	yes	1 yr @ -40°C
Fast cure version of ABLEBOND 8175 adhesive for surface mount component attach applications.							
ABLEBOND 8177	24 hrs	4 min @ 130°C	6300 psi	0.0001 ohm-cm	n/a	n/a	1 yr @ -40°C
Chip attach adhesive for applications which require high thermal conductivity. Cures rapidly at low temperatures. Can be used with thermal sensitive devices without damaging the assembly.							
ABLEBOND 8370	5 days	1 hr @ 150°C	2500 psi	0.0005 ohm-cm	0.50 %	no	1 yr @ -40°C
Gold-filled, solvent-free epoxy adhesive designed for hybrid applications where silver migration is a critical concern.							
ABLEBOND 8700 E	4 days	1 hr @ 175°C or 2 hrs @ 160°C	5100 psi	0.0002 ohm-cm	0.30 %	yes	1 yr @ -40°C
Silver-filled, one component epoxy adhesive designed for hybrid component attach. This adhesive provides excellent adhesion to component termination surfaces, such as gold, without forming fissures or cracks.							
ABLEBOND 8260	3 days	3 min @ 150°C or 5 min @ 130°C	5000 psi	0.0005 ohm-cm	n/a	no	1 yr @ -40°C
One component, electrical conductive epoxy adhesive designed for surface mount component attach applications. Applied by syringe dispense or screen print.							
ABLEBOND 8384	7 hrs	3 min @ 115°C or 30 sec @ 150°C	7000 psi	0.03 ohm-cm	0.20 %	no	1 yr @ -40°C
Fast cure, excellent dispensibility with minimal tailing and stringing, excellent adhesion to gold plated surfaces.							
AMICON® 50262-5	n/a	10 min @ 120°C or 2 hrs @ 80°C	>5 MPA (Lap Shear)	<0.005 ohm-cm	n/a	no	3 mths @ 0°C
One component, low temperature curing, electrically conductive adhesive applied by syringe dispense. Designed for heat sensitive applications.							

Product	Work Life@ Room Temperature	Cure Schedule(s)	Die Shear Strength (80 mil ² IC)	Volume Resistivity	Weight Loss @ 300°C	Meets 5011	Storage Life
AMICON C 850-5 A	n/a	60 min @ 125°C or 30 min @ 150°C	600 psi (50 mil ² IC)	<0.001 ohm-cm	n/a	no	6 mths @ 0°C

One component, silver-filled epoxy die attach adhesive. High electrical and thermal conductivity. High strength at wire bond temperatures. Good green strength, no resin bleed, applied by syringe dispense or stencil print.

AMICON 50262-3	>1 week	45 min @ 100°C or 10 min @ 150°C	>5 MPA (Lap Shear)	<0.005 ohm-cm	n/a	no	6 mths @ -20°C
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One component, low temperature curing, electrically conductive epoxy adhesive which can be applied by syringe dispense or stencil print. Designed for use when heat sensitive materials are involved and conventional soldering is impractical.

AMICON C 840-8	4 weeks	60 min @ 125°C or 30 min @ 150°C	1100 psi (Tensile Shear)	<0.001 ohm-cm	n/a	no	1 yr @ 0°C
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One component, heat cured, electrically and thermally conductive, easily dispensed fast cure thixotropic paste epoxy adhesive. Good green strength before cure. Resists wire bonding forces after cure. Cures quickly at temperatures as low as 125°C, is non-bleeding, non-corrosive, and contains no fluoride for LED, IC chip bonding and other electronic assembly applications.

AMICON C 990 J	3 weeks	60 min @ 150°C	5280 psi (50 mil ² IC)	0.0003 ohm-cm	n/a	no	6 mths @ 0°C
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Low temperature cure, low levels of extractable ionic contaminants, suitable for syringe dispense, screen print or pin transfer, low voiding under chip and low bleeding on ceramic substrates.

Electrically Insulative

ABLEBOND 789-3	3 months	30 min @ 150°C or 1 hr @ 125°C	5000 psi	2 x1014 ohm-cm	0.28% @ 250°C	no	6 mths @ 5°C or 1 yr @ -40°C
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Moisture resistant, one component, solvent-free epoxy designed for substrate attach and package sealing. Ideal for applications where ABLEFILM 550 preforms are not suitable. Also designed in a thermally conductive version.

ABLEBOND 789-4	3 months	30 min @ 150°C or 1 hr @ 125°C	3500 psi	6 x1014 ohm-cm	0.28%	no	6 mths @ 5°C or 1 yr @ -40°C
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One component, thermally conductive adhesive designed for applications such as substrate attach, sealing microelectronic packages and heat sink attach. It provides four times more thermal conductivity than unfilled epoxy adhesives.

ABLEBOND 967-3	2 days	6 hrs @ 65°C or 5 min @ 150°C	3850 psi	2 x1013 ohm-cm	n/a	no	Premixed & Frozen: 1 yr @ -40°C Kits: 6 mths @ 25°C
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Electrically insulating version of ABLEBOND 967-1 adhesive. Solvent-free adhesive designed for applications that require lower-than-normal cure temperatures.

ABLEBOND 8700 K	30 days	1 hr @ 175°C or 2 hrs @ 160°C	6000 psi	3 x1014 ohm-cm	0.35%	yes	1 yr @ -40°C
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Electrically insulating version of ABLEBOND 8700E adhesive. Provides excellent adhesion to thin film and thick film gold surfaces.

AMICON E 3503	n/a	5 min @ 150°C 30 min @ 100°C	1800 psi	n/a	n/a	no	6 mths @ -20°C
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One component, low temperature curing, thermally conductive epoxy adhesive developed for microelectronic applications, specifically die attach. Cures at moderate temperatures allowing use on heat sensitive materials. Syringe dispensed.

AMICON XTE 80086-1	>4 days	30 min @ 120°C or 15 min @ 150°C	>10 MPA (Lap Shear)	n/a	n/a	no	6 mths @ -20°C
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One component, low temperature curing, thermally conductive epoxy adhesive developed for COB die attach applications. Cures at moderate temperatures allowing use on heat sensitive materials.

AMICON ME 990 J	2 weeks	60 min @ 150°C	n/a	n/a	n/a	no	6 mths @ 0°C
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Low temperature cure, high thermal conductivity, low levels of extractable ionic contaminants, syringe dispensed.